

Date: 23.09.2014

Federal Communications Commission Authorization and Evaluation Division 7435 Oakland Mills Road Columbia, MD 21046

Attn: OET Dept.

Ref: FCC Class II Permissive change for FCC ID: WNS-020000007

(Original Grant date: 11/13/2008)

Applicant: Delphi Delco

Dear Examiner,

This is to request a Class II permissive change for FCC ID: WNS-020000007 originally granted on 11/13/2008.

The major changes filed under this application are:

All listed products in the specification description are new revisions of old products (certified in 2008) due to several discontinued components. With respect to the FBDII building block PCB design as well SW is identical with the initial homologation!

All changed FBDII relevant components are drop in replacements and are described in the next pages!

The RF part still remains the same!

If you have any questions regarding this application, please feel free to contact me.

Sincerely yours,

CSA Group Bayern GmbH
Ohmstrasse 1 - 4
94342 Strasskirchen

Name: Thomas Ring

Titel: Teamleader Global Market Access

CSA Group Bayern GmbH

Ohmstrasse 1-4

94342 Strasskirchen, Germany

Supplier Suggestion Change Request # 52932 Date Submitted: 24-Sep-2013

	CON	NTACT INFORMATION	Date Submitted: 24-Sep-201
	COI	VIACT IN ORIVIATION	
	Enter	red By	Owner
Name	Herr Vital	i Michaelis	Herr Vitali Michaelis
Title		err	Herr
Phone		1 67 3367	+49 7131 67 3367
Fax		1 67 3163	+49 7131 67 3163
Email	vitali.michael	is@atmel.com	vitali.michaelis@atmel.com
Receive Status Email	l l	N	Υ
Cumplion Illtimata Nama	ATMEL CORD		
Supplier Ultimate Name	ATMEL CORP		
Supplier Ultimate DUNS	121385264 ame Atmel	Supplier Manufa	cturing Location Duns 266358084
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Product Application			
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Delphi Buyer Phone		Delphi Engineer Phone	
Delphi SQE / AQE Name De	enys Chock		
Is this an Emergency ? No Ye	es		
Other Delphi Contact	Title	Name	Phone
Other Delphi Contact	<u>Title</u>	<u>Name</u>	<u>Phone</u>
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Supplier Suggestion Change Request # 49279

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		CONTACT INFORMATION		
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		itered By	Owner	
		ry Rosselot	Sherry Rosselot	
	Title		Administrator	
		-459-5355	765-459-5355	
		-455-4031	765-455-4031	
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Supplier Ultimate Name	NVD CEMICO	NDUCTORS N.V.		
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	AFF	ECTED PART INFORMATION		
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	n, DA31, DAT3, Megamos, Fub	a, Hungary		
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Decision Application	Halinania			
Product Application	Unknown	But we util	W I I	
Delphi Buyer Name	May Leong	Product Engineer	5	
Delphi Buyer Phone	+65-6450-8655	Delphi Engineer I	Phone Unknown	
Delphi SQE / AQE Name	Burkhard Exner / Loris F	Rolfe		
Is this an Emergency?	No O Yes			
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Supplier Suggestion Change Request # 48319

					Da	ite Submitted : 29-Oct-2012
		CONTAC	CT INFORMA	TIÓN		
		Entered E	Βv		Owner	
	Name	Sherry Ross	selot		Sherry Rosselot	
	Title	•			Administrator	
	Phone	765-459-53	355		765-459-5355	
	Fax	765-455-40	031		765-455-4031	
	Email	sherry.rosselot@	nxp.com		sherry.rosselot@nx	p.com
Receive Status	Email	N			Υ	
Supplier Ultimate Name		XP SEMICONDUCT	ORS N.V.			
Supplier Ultimate DUNS		14955513	N	0		445007005
Supplier Manufacturing Loc		XP Semiconductors	Netnerlads		turing Location Duns	415097385
Supplier Manufacturing Loc	•	ijmegen		Supplier Manufac	turing Location State	
Supplier Manufacturing Loc	cation Country N					
		AFFECTED	PART INFOR	MATION		
Is this	s a pass-thru or d	irect ship product?	®No ∩Ye	es		
Ship To Location(s) DA31,	-					
	Electronics & Safe			mon a Draga		
Region North		,	Com	modity Group	Electrical	
· ·						
Delphi Part # / PO #(for Indirect)	Revisi	<u>on</u>	D	rawing No.	Part / Project Name	
28136407	Α			Unknow	Unknown	
20130407	^	Addit	ional Parts	OTIKITOW	Olikilowii	
28148503	А	Addit		Unknown	Unknown	
201.10000				·······	• • • • • • • • • • • • • • • • • • • •	
	Supplier Pa		pplier Part Na			
	TJA1021T/2		Transceiver	SO8		
		dditional Part Num				
	TJA1021T/	10/C LIN	l Transceiver	SO8		
Decision Associantian	Union					
Product Application	Unknown	_	Dan desat	Englished Name	D A-i-	
Delphi Buyer Name	May Leong Unknown)		Engineer Name	Ramon Aziz	
Delphi Buyer Phone Delphi SQE / AQE Name		Exner / Loris Rolfe	Deiphili	Engineer Phone	Unknown	
Is this an Emergency ? (a)		Allei / Lolis Rolle				
	_					
Other Delphi Contact		<u>Title</u>		<u>Name</u>	<u>Phone</u>	
1 2						
		DEFINE C	CHANGE REC	NIEST		
		DETINE	MANUE REG	OLUT		
			<u>Title</u>			
		Quality Improver	ments to TJA1	021T LIN Transceiv	er er	
Detail Description of Chang			- 4-11	-04 - 0		- DA400TMV04: LIDD
NXP TJA1021T LIN transceiv passivation - Mould compoun	ers out of ABCD-3 d (Sumitomo EME	6210 to Nitto GF747	ie foliowing qu 'n) - Die attach	ality improvements material (Ablebond	made: - Process update to I 8390P to Henkel OMI-51	9) - Roughened ton side
leadframe (already used in ot	her transceivers, re	eference SCR30756)) - Wafer thick	ness (380um to 280	lum) - Bondwire diameter	and material (25um AuBe to
20um AuPd) - Sawlane chang						scritpion will also change:
TJA1021T/10/C to TJA1021T	/10/CM and TJA10)21T/20/C to TJA102	21T/20/CM - N	o change to the exis	siting NXP datasheet.	
Reason for Change	i angaing gualituig	marayamanta and ina		rdinations and not fo	rom on condentaine evalit	, ianua
These changes are a result of	ongoing quality if	nprovements and inc	Justriai standa	idizations and not if	om any undenying quality	rissue
Reference PCR Number :						
		CHA	NGE IMPAC	Γ		
		Types	of Improvem	ent		
		71				
☐ Cost	Quality		Delivery	□ Lo	ogistics	
Consumer Appeal	Maintenanc	e & Support	Equipment Up	grade S	oftware Enhancement	
□ Network Capability						
			Affects			
- .					—	
Appearance	Function		⊠ Proc		Location char	nge
	☐ Packag	jing	☐ Cust	omer Interface		
Impact Change will have						
A more robust part. Should ha	ave no negative im	pact to customer.				
Patients discrete as a second second		4 84 -1				
Estimated Implementation Lead Tim	e:	1 Months	Commi-	Parte to Dolahi De-		03 Doc 2012
Requested Disposition Date : Component Data / Test Data to Delp	hi Bv :	31-Mar-2013 29-Oct-2012		Parts to Delphi By Date for Production	: on at Supplier Facility :	03-Dec-2012 31-Mar-2013
Tamponom Data, Tool Data to Dolp	··· y ·	20 001 2012	_001100			a. =0.0

Supplier Suggestion Change Request # 48318

				Date Submitted: 29	
		CONTACT INFORM	ATION		
		Entered By		Owner	
		Entered By		Owner Shorry Possolet	
	Title	nerry Rosselot		Sherry Rosselot Administrator	
		65-459-5355		765-459-5355	
		65-455-4031		765-459-5555 765-455-4031	
		osselot@nxp.com		sherry.rosselot@nxp.com	
Receive Status		N		Υ	
1000.00	Lilian	14		•	
Supplier Ultimate Name	NXP SEMIC	CONDUCTORS N.V.			
Supplier Ultimate DUNS	414955513				ļ
Supplier Manufacturing Lo	cation Name NXP Semico	ondcutors Netherlands	Supplier Manufac	turing Location Duns 415097385	į
Supplier Manufacturing Loc	cation City Nijmegen		Supplier Manufac	turing Location State	ļ
Supplier Manufacturing Loc	cation Country NETHERLA	NDS			
	AF	FECTED PART INFO	RMATION		
	s a pass-thru or direct ship	product? No O	′es		
Ship To Location(s) Fuba					
·	i Electronics & Safety		_		
Region Europ	е	Со	mmodity Group	Electrical	
Delphi Part # / PO #(for	Revision		Drawing No.	Part / Project Name	
<u>Indirect)</u>					ļ
28086447	A		Unknown	Unknown	ļ
		Additional Parts			ļ
28117864	A		Unknown	Unknown	
	Complier Bort #	Complier Port I	lama		
	Supplier Part #	Supplier Part N			
	PQJ7980AHN/C0CH	LoPSTer 1.2	25		
		Part Numbers			
	PQJ7980AHN/C0DL	LoPSTer 1.2	25		
Product Application	Unknown				
Delphi Buyer Name	Unknown	Produ	ct Engineer Name	Unknown	
Delphi Buyer Phone	Unknown		Engineer Name	Unknonw	
Delpili Buyer Frione	Ulkilowii	Deibiii	Engineer Frione	UNKHONW	
Delphi SOF / AOF Name	Rurkhard Exper				
Delphi SQE / AQE Name Is this an Emergency?	Burkhard Exner				
Is this an Emergency?	No O Yes				
Is this an Emergency? Other Delphi Contact	No O Yes		<u>Name</u>	<u>Phone</u>	
Is this an Emergency? Other Delphi Contact 1	No O Yes		<u>Name</u>	<u>Phone</u>	
Is this an Emergency? Other Delphi Contact	No O Yes <u>Title</u>	DEFINE CHANCE DE		<u>Phone</u>	
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Other Delphi Contact 1 2 Detail Description of Change	No Yes Title Quality	Title Improvements to LoP	QUEST STer 1.25 PQJ7980A	HN	_
Other Delphi Contact 1 2 Detail Description of Change NXP is making the following of the contact of the conta	No Yes Title Quality ge Proposal design, manufacturing and tes	Title Improvements to LoPs st changes to the listed	QUEST STer 1.25 PQJ7980Al I types: -New passiva	HN tion stack (HDP stack) This will give an incre	
Other Delphi Contact 1 2 Detail Description of Change NXP is making the following of mechanical robustnessWafe	No Yes Title Quality Proposal design, manufacturing and tes ercoating change which will a	Title Improvements to LoPs st changes to the listed	QUEST STer 1.25 PQJ7980Ald types: -New passiva al robustnessImpro	HN tion stack (HDP stack) This will give an incr ved leadframe version. This will increase rol	oustness
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Other Delphi Contact 1 2 Detail Description of Chang NXP is making the following of mechanical robustnessWafagainst moistureMoisture S regulator thresholds which wire	Quality Proposal Jesign, manufacturing and testercoating change which will a tensitivity Level will change frill improve power output control.	Title Improvements to LoP st changes to the lister also improve mechanic om MSL-3 to MSL-2a olPA and VCO isola	QUEST STer 1.25 PQJ7980Ald types: -New passiva all robustnessImpro-EMC (clock spurs) to tion improvement which	HN tion stack (HDP stack) This will give an increved leadframe version. This will increase role improve EMC performance at clock input -/ch will improve robustness at TX application	oustness Adjust PA with
Other Delphi Contact 1 2 Detail Description of Change NXP is making the following of mechanical robustnessWafagainst moistureMoisture S regulator thresholds which will SAW filter (1.25 only) -ESD in	Quality Proposal design, manufacturing and tesercoating change which will a densitivity Level will change from the provenent> Specification	Title Improvements to LoP- st changes to the lister also improve mechanic om MSL-3 to MSL-2a olPA and VCO isola upgrade -DC testing P	QUEST STer 1.25 PQJ7980Al types: -New passiva al robustnessImpro -EMC (clock spurs) to tion improvement which A which will give test	HN tion stack (HDP stack) This will give an increved leadframe version. This will increase role improve EMC performance at clock input -/	oustness Adjust PA with on for
Detail Description of Change NXP is making the following of mechanical robustnessWafagainst moistureMoisture S regulator thresholds which with SAW filter (1.25 only) -ESD in PQJ7980AHN/COCH, once questions and the same of the sa	Quality Proposal design, manufacturing and tesercoating change which will a lensitivity Level will change from the provement—s Specification ualified will be PQJ7980AHN/	Title Improvements to LoP st changes to the lister also improve mechanic om MSL-3 to MSL-2a ollPA and VCO isola upgrade -DC testing P COIH -New type descri	QUEST STer 1.25 PQJ7980Al types: -New passiva al robustnessImpro -EMC (clock spurs) to tion improvement whi A which will give test ription for PQJ7980Al	HN tion stack (HDP stack) This will give an increved leadframe version. This will increase rol improve EMC performance at clock input -4 ch will improve robustness at TX application coverage improvement -New type descriptic	oustness Adjust PA with on for
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